



<https://ewh.ieee.org/conf/edtm/2021>

5th IEEE Electron Devices Technology and Manufacturing (EDTM) Conference, 2021

EDTM2021 Theme: **Intelligent Technologies for Smart and Connected Life**

Chengdu, China, March 9th–12th, 2021

New Dates: April 8-11, 2021 (Hybrid)

The **IEEE Electron Devices Technology and Manufacturing (EDTM) Conference 2021** is a four-day meeting to be held in Chengdu, China, during **April 8th to 11th, 2021**. Sponsored by IEEE *Electron Devices Society* (EDS), EDTM is a premier conference, providing a unique forum for discussions on a broad range of device/manufacturing-related topics. EDTM rotates among the hot-hubs of semiconductor manufacturing in Asia, coming to China in 2021.

Whether you are seeking to enhance brand recognition, reinforce your reputation as an industry leader, or establish a new business, EDTM 2021 sponsorship will enable you achieve your goals in this highly attended conference.

Sponsorship Benefits:

All sponsors will be recognized in the EDTM 2021 Program Book, Proceedings and USB sticks, and acknowledged during Plenary and Technical Sessions. Additional benefits are:

Diamond (US\$16K):

- Company logo projected during Plenary Session
- Company logo on all technical session starting slides
- Banner at registration identifying your company as Diamond sponsor
- Company logo at the Reception and Poster Sessions
- 3 complementary full conference Registration
- 3 complementary Tutorial/Short Course Registration
- 2 complementary exhibition booths

Platinum (US\$12K):

- Company logo on all technical session starting slides
- Banner at registration identifying your company as Platinum sponsor
- Company logo at the Reception and Poster Sessions
- 2 complementary full conference Registration
- 2 complementary Tutorial/Short Course Registration
- 1 complementary exhibition booth

Gold (US\$6K):

- Large-size font at registration identifying your company as Gold sponsor
- Company logo at the Reception and Poster Sessions
- 1 complementary full conference Registration
- 1 complementary Tutorial/Short Course Registration
- 1 complementary exhibition booth

Silver (US\$4K):

- Company logo at the Reception and Poster Sessions
- 1 complementary full conference Registration

Bronze (US\$3K):

- Company logo at the Reception and Poster Sessions

Business & Exhibition Night (US\$6K):

- Company logo at the **Business & Exhibition Night** (jointly with Poster II Session & Exhibition on 4/10)
- Recognized as Gold sponsor with associated benefits

Student Program (US\$6K):

- Provides free registration to students participating in student volunteer program
- Recognized as Gold sponsor with associated benefits

General Chair:

Albert Wang (UC Riverside)

aw@ece.ucr.edu

General Co-Chair:

Tianchun Ye (IMECAS)

tcye@ime.ac.cn

TPC Chair:

Huaqiang Wu (Tsinghua U)

wuhq@tsinghua.edu.cn

TPC Co-Chair:

Subramanian Iyer (UCLA)

s.s.iver@ucla.edu

Steering Committee:

Kazunari Ishimaru (Chair, Kioxia)

Ru Huang (Co-Chair, Peking U)

Fernando Guarin (Globalfoundries)

Tsu-Jae King Liu (UC Berkeley)

Ming Liu (IMECAS)

Meyya Meyyappan (NASA)

Samar Saha (Prosperic Devices)

Ravi Todi (Western Digital)

Albert Wang (UC Riverside)

Huaqiang Wu (Tsinghua U)

Tianchun Ye (IMECAS)

Bo Zhang (UESTC)

Bin Zhao (EBI)

Xuecheng Zou (HUST)

Secretariat:

Chengdu Tinglan Meeting Co., Ltd.

Email: nancy@tlan-group.com

Contacts:

Sponsorships & Exhibition Chairs

He Qian, qianh@tsinghua.edu.cn

Bill Nehrer, bill.nehrer@gmail.com

Xuecheng Zou, esxczou@hust.edu.cn

General Chair:

Albert Wang, aw@ece.ucr.edu



<https://ewh.ieee.org/conf/edtm/2021>

5th IEEE Electron Devices Technology and Manufacturing (EDTM) Conference, 2021

EDTM2021 Theme: **Intelligent Technologies for Smart and Connected Life**
 Chengdu, China, April 8th - 11th, 2021

Sponsorship Category

Sponsorship Level	Costs (US\$)
Diamond	16K
Platinum	12K
Gold	6K
Silver	4K
Bronze	3K
Business & Exhibition Night	6K
Student Program	6K

Sponsorship Benefit Summary

Sponsorship Benefits	Diamond	Platinum	Gold	Silver	Bronze	Business & Exhibition Night	Student Program
Company logo projection at Plenary Session	Yes	No	No	No	No	No	No
Company logo on all technical session starting slides	Yes	Yes	No	No	No	No	No
Banner at Registration identifying your company sponsor	Yes	Yes	Yes	No	No	Yes	Yes
Company logo at the Reception and Poster Sessions	Yes	Yes	Yes	Yes	Yes	Yes	Yes
Number of complementary full conference Registration	3	2	1	1	0	1	1
Number of complementary Tutorial/Short Course Registration	3	2	1	0	0	1	1
Number of complementary exhibition booths	2	1	1	0	0	1	1
Company logo at the Business & Exhibition Night	Yes	Yes	No	No	No	Yes	Yes

EDTM2021 will go **HYBRID** comprising a normal **in-Person/on-Site meeting** with large attendance and a **Virtual Component** (presentation, participation and exhibition) for those with travel restriction due to COVID-19.

Contacts:

Sponsorships & Exhibition Chairs

He Qian, qianh@tsinghua.edu.cn

Bill Nehrer, bill.nehrer@gmail.com

Xuecheng Zou, estxczou@hust.edu.cn

Aabid Husain, aabid@atomera.com

General Chair:

Albert Wang, aw@ece.ucr.edu

Secretariat:

Chengdu Tinglan Meeting Co., Ltd., nancy@tlan-group.com